# PATENT ASSIGNMENT

Electronic Version v1.1
Stylesheet Version v1.1

## SUBMISSION TYPE:

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<th>NEW ASSIGNMENT</th>
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## NATURE OF CONVEYANCE:

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## CONVEYING PARTY DATA

<table>
<thead>
<tr>
<th>Name</th>
<th>Execution Date</th>
</tr>
</thead>
<tbody>
<tr>
<td>Katsuhiro Tomoda</td>
<td>06/25/2007</td>
</tr>
<tr>
<td>Shiyuki Kanisawa</td>
<td>06/21/2007</td>
</tr>
<tr>
<td>Hidetsugu Namiki</td>
<td>06/21/2007</td>
</tr>
</tbody>
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## RECEIVING PARTY DATA

<table>
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<tr>
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<th>Execution Date</th>
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<tr>
<td>Sony Corporation</td>
<td></td>
</tr>
<tr>
<td>Street Address: 1-7-1 Konan, Minato-ku</td>
<td></td>
</tr>
<tr>
<td>City: Tokyo</td>
<td></td>
</tr>
<tr>
<td>State/Country: JAPAN</td>
<td></td>
</tr>
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<table>
<thead>
<tr>
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<th>Execution Date</th>
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<tbody>
<tr>
<td>Sony Chemical &amp; Information Device Corp.</td>
<td></td>
</tr>
<tr>
<td>Street Address: 1-11-2, Osaki, Shinagawa-ku</td>
<td></td>
</tr>
<tr>
<td>City: Tokyo</td>
<td></td>
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<td>State/Country: JAPAN</td>
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## PROPERTY NUMBERS Total: 1

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<tr>
<th>Property Type</th>
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<tbody>
<tr>
<td>Application Number</td>
<td>11778736</td>
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## CORRESPONDENCE DATA

Fax Number: (312)827-8185

Correspondence will be sent via US Mail when the fax attempt is unsuccessful.

Email: patents@bellboyd.com

Correspondent Name: Thomas C. Basso

Address Line 1: Bell, Boyd & Lloyd LLP, P.O. Box 1135

Address Line 4: Chicago, ILLINOIS 60690-1135

## ATTORNEY DOCKET NUMBER:

113380-007

NAME OF SUBMITTER:

Thomas C. Basso
ASSIGNMENT

WHEREAS, the undersigned, to wit: Katsuhiro Tomoda, Shiyuki Kanisawa and Hidetsugu Namiki (hereinafter “ASSIGNORS”), are the lawful owners of an invention entitled: DEVICE, METHOD OF MANUFACTURING DEVICE, BOARD, METHOD OF MANUFACTURING BOARD, MOUNTING STRUCTURE, MOUNTING METHOD, LED DISPLAY, LED BACKLIGHT AND ELECTRONIC DEVICE, for which a patent application of the United States will be filed in the United States Patent and Trademark Office or was filed on July 17, 2007 in the United States Patent and Trademark Office having Application Serial No. 11/778,736;  

AND WHEREAS, Sony Corporation, a corporation duly organized and existing under the laws of Japan and having its principal office and place of business at 1-7-1 Konan, Minato-ku, Tokyo, 108-0075 Japan, and Sony Chemical & Information Device Corporation, a corporation duly organized and existing under the laws of Japan and having its principal office and place of business at 1-11-2, Osaki, Shinagawa-ku, Tokyo, Japan (hereinafter “ASSIGNEES”) desires to acquire the entire right, title, and interest therein;  

NOW, THEREFORE, in consideration of One Dollar ($1.00) and other good and valuable consideration, the receipt and sufficiency of which are hereby acknowledged, said ASSIGNORS do hereby sell, assign, and transfer, and hereby set over unto ASSIGNEES, its successors, assigns and legal representatives, the full and exclusive right, title and interest to said invention in the United States of America and all foreign countries, including, without limitation, said invention as described in the aforesaid application, to be held and enjoyed by said ASSIGNEES, its successors and assigns, as fully and entirely as the same would have been held and enjoyed by said ASSIGNORS had this assignment and sale not been made, including, without limitation, all rights to the aforesaid application and to any United States Letters Patent therefor, when issued together with all improvements thereon and betterments thereof, all related applications including, but not limited to, divisions, continuations, continuations-in-part, reissues and reexaminations thereof and substitutions of or for said application, and all foreign rights including the right to make application for Letters Patent for said inventions in any and all foreign countries and the right to claim priority as to the filing date under the International Convention on the basis for the aforesaid application for United States Letters Patent; and ASSIGNORS hereby authorize and request the Commissioner of Patents to issue all Letters Patent issuing therefrom to ASSIGNEES, for its interest as ASSIGNEES, its successors, assigns and legal representatives.  

ASSIGNORS hereby agree to execute any papers, provide any information and testify in any interference or litigation at the request of ASSIGNEES, its successors, assigns and legal representatives, when deemed essential to ASSIGNEES', its successors', assigns' and legal representatives' full enjoyment, protection, enforcement and title in and to such invention and rights hereby transferred.  

ASSIGNORS furthermore agree upon request of said ASSIGNEES, its successors, assigns and legal representatives, and without further remuneration, to execute any and all papers desired by said ASSIGNEES, its successors, assigns and legal representatives, for the filing and
granting of foreign applications and the perfecting of title thereto in said ASSIGNEES, its successors, assigns and legal representatives.

It is hereby authorized that the attorney of record in the above-referenced patent application insert the serial number and filing date of the patent application, if applicable, in the spaces identified above.
Signature
Katsuhiro Tomoda

Name: Katsuhiro Tomoda

Address: c/o Sony Corporation
1-7-1 Konan, Minato-ku
Tokyo, 108-0075 Japan

Date Signed
June 25, 2007

Before me personally appeared the person whose name is subscribed to the foregoing instrument, and executed the foregoing instrument in my presence for the purpose contained therein, by signing his/her name hereto.

Signature
Kayoko Fujio

Date Signed
June 25, 2007
Signature

Name: Shiyuki Kanisawa

Date Signed: 2007.6.21

Address: c/o Sony Chemical & Information Device Corporation
1-11-2, Osaki, Shinagawa-ku
Tokyo, Japan

Before me personally appeared the person whose name is subscribed to the foregoing instrument, and executed the foregoing instrument in my presence for the purpose contained therein, by signing his/her name hereto.

Signature

Date Signed: Jun.21, 2007

Page 4 of 5
Signature

Hidetsugu Namiki

Name: Hidetsugu Namiki

Address: c/o Sony Chemical & Information Device Corporation
1-11-2, Osaki, Shinagawa-ku
Tokyo, Japan

Before me personally appeared the person whose name is subscribed to the foregoing instrument, and executed the foregoing instrument in my presence for the purpose contained therein, by signing his/her name hereto.

Signature

Takashi Murayama

Date Signed

2007. 6. 21

Date Signed

Jun. 21, 2007